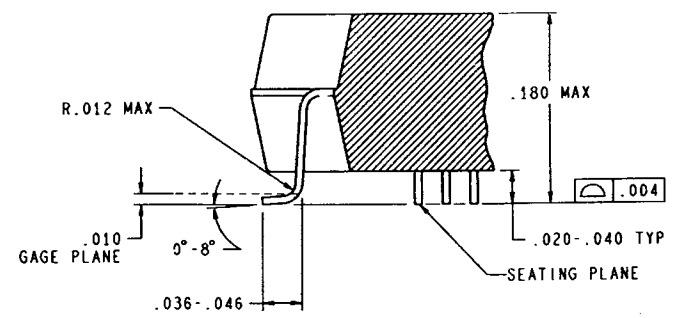
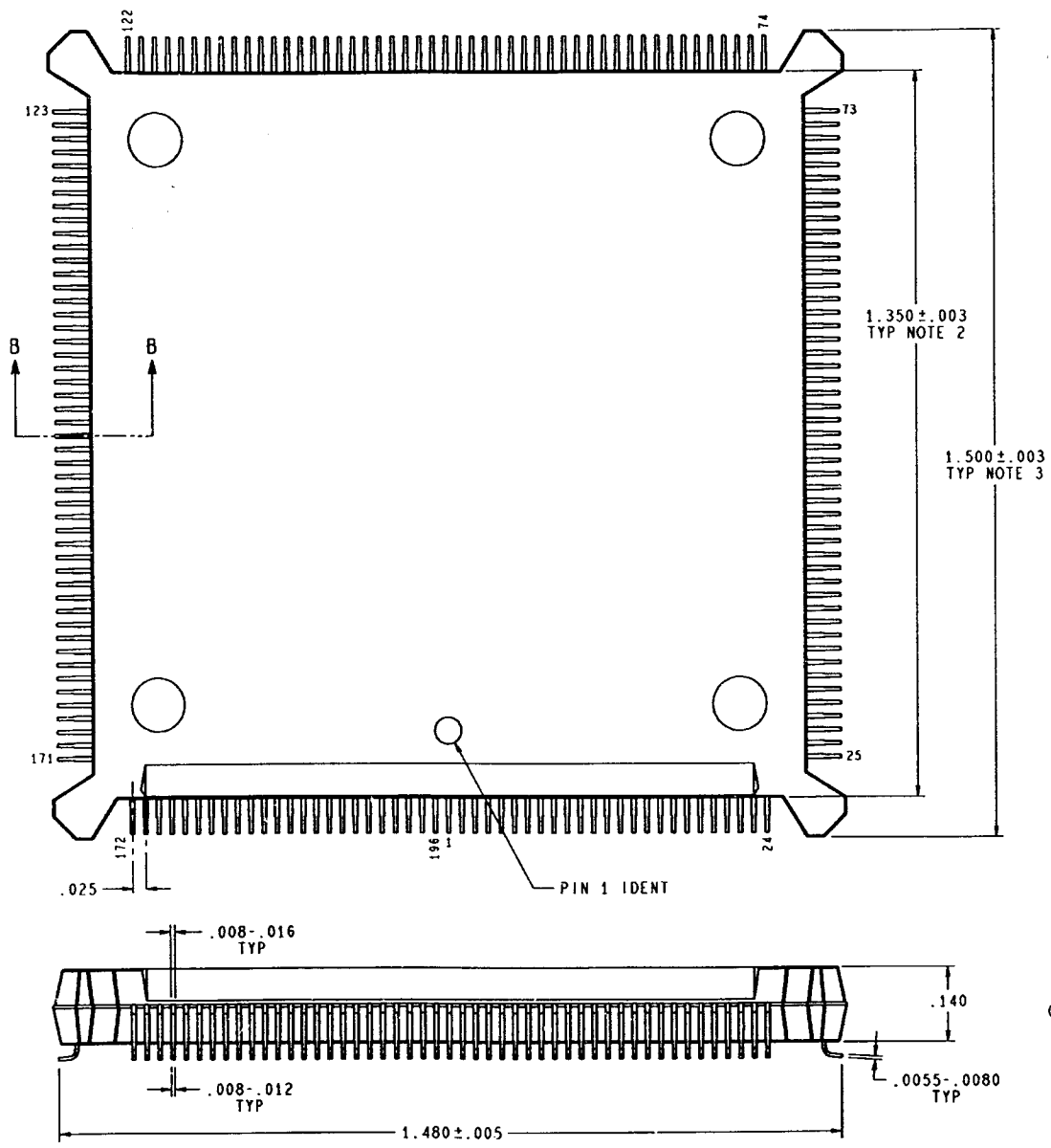


REVISIONS				
LTG	DESCRIPTION	E.C.N.	DATE	BY/APP'D
C	REVISE AND REDRAW ALL IN INCH DIMS.	11103	09/01/95	DEG/HJ



NOTES: UNLESS OTHERWISE SPECIFIED

- STANDARD LEAD FINISH: 300 MICROINCHES MINIMUM SOLDER PLATING (85/15) THICKNESS ON COPPER.
- DIMENSION DOES NOT INCLUDE MOLD PROTRUSION. MAXIMUM ALLOWABLE MOLD PROTRUSION $.010$ IN PER SIDE.
- DIMENSION DOES NOT INCLUDE MOLD PROTRUSION. MAXIMUM ALLOWABLE MOLD PROTRUSION $.006$ IN PER SIDE.
- REFERENCE JEDEC REGISTRATION MO-069, VARIATION AG, DATED OCT/90.

DIMENSIONS ARE IN INCHES

SECTION B-B
SCALE: 12X

APPROVALS		DATE	National Semiconductor		
DRAWN <i>D.E. Grady</i>		09/01/95	2900 Semiconductor Dr., Santa Clara, CA 95052-8090		
BY TO. CHK. <i>[Signature]</i>		3/1/85	PLASTIC QUAD FLATPACK, 196 LEAD		
ENGR. CHK. <i>H.J. Kim</i>		9/13/95			
PROJECTION		SCALE	SIZE	DRAWING NUMBER	REV
		N/A	C	MKT-VF196A	C
DO NOT SCALE DRAWING					SHEET 1 of 1